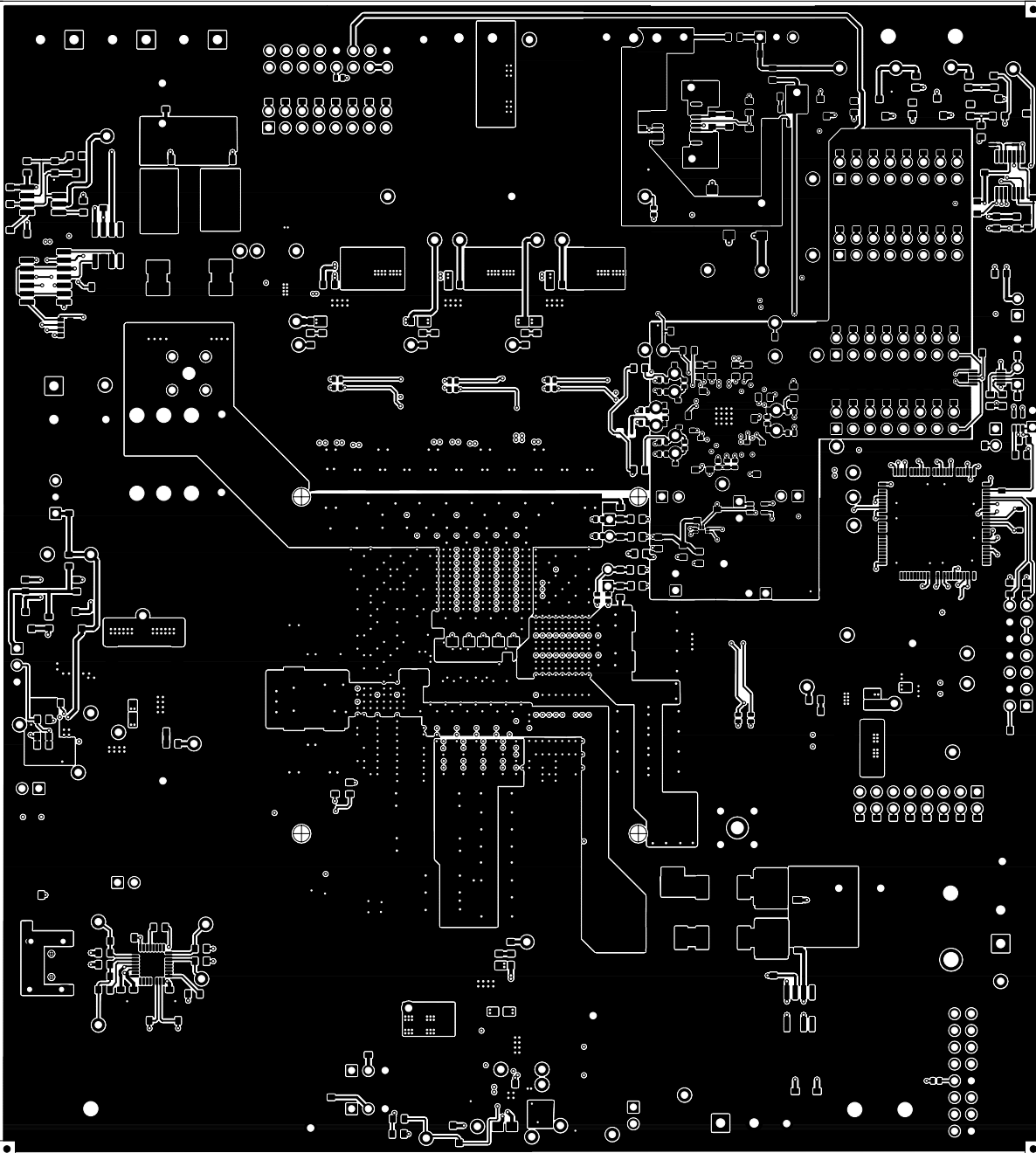
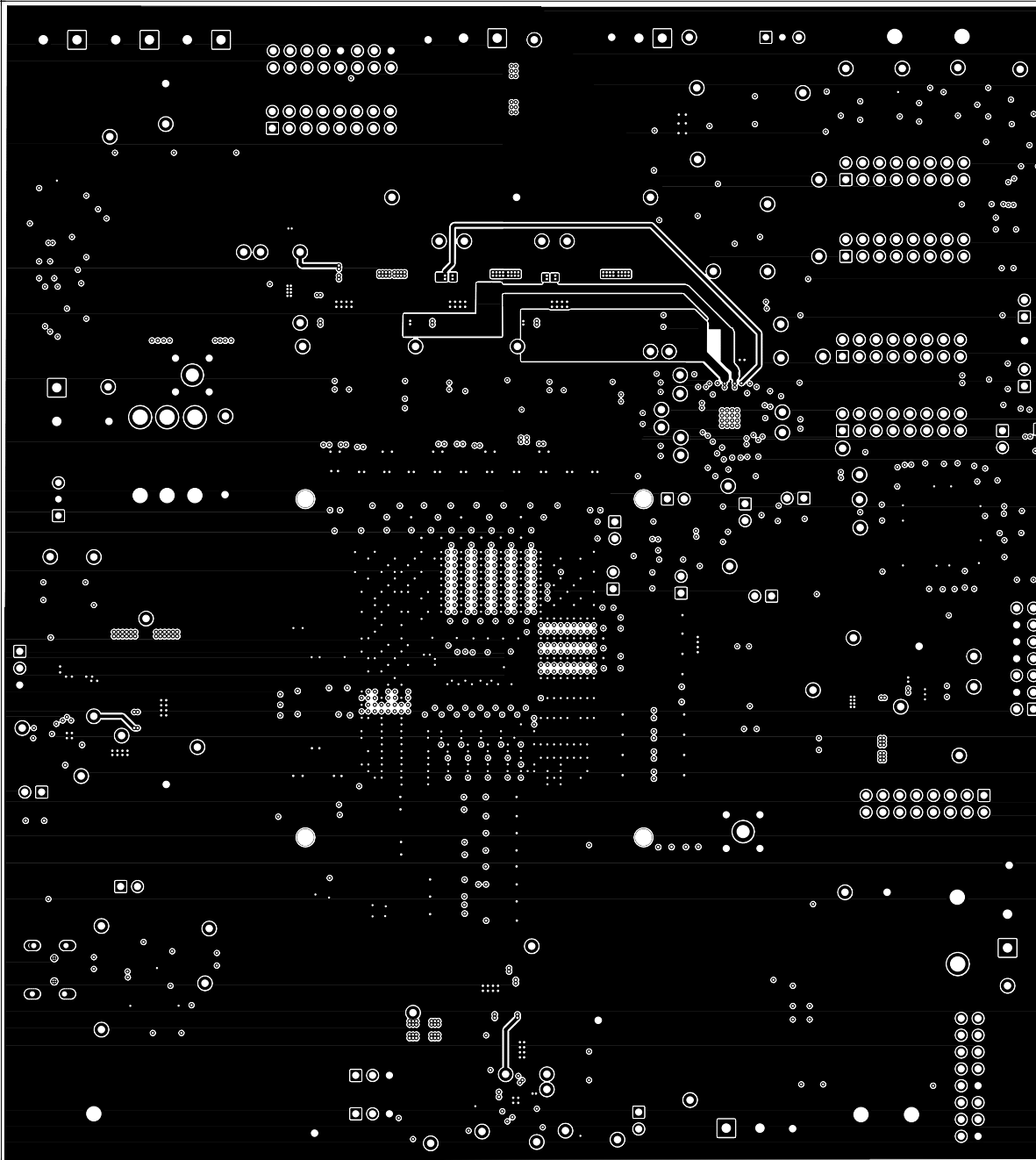


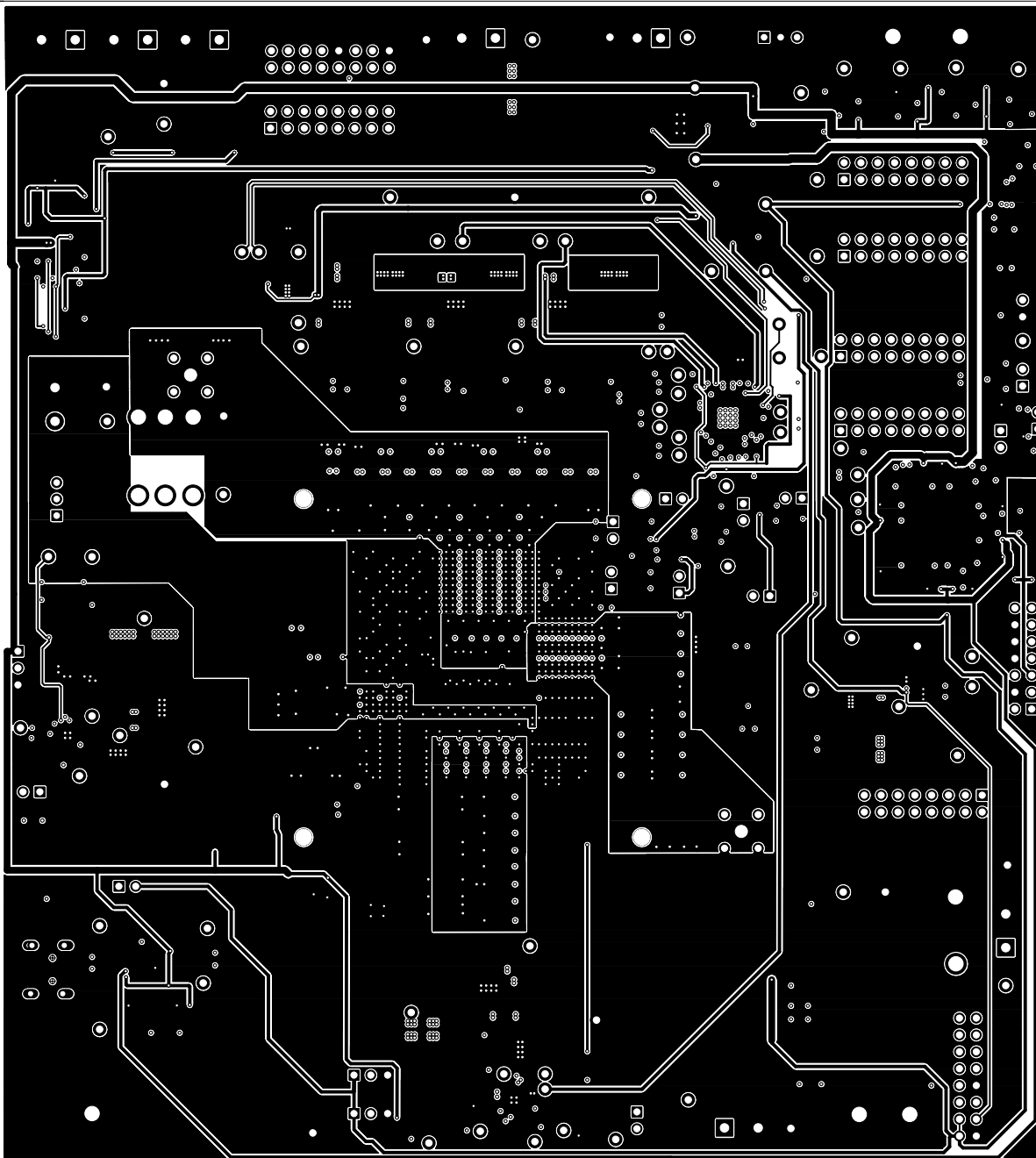
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. HPA751	Rev. A	L1										
Date: 11/30/2010	Filename: HPA751A.pcb	Engineer: Nancy Zhang	PCB Dgnr: Rama V	Modified Date: Mon Nov 14, 2011								Time Stamp: 17:06:21



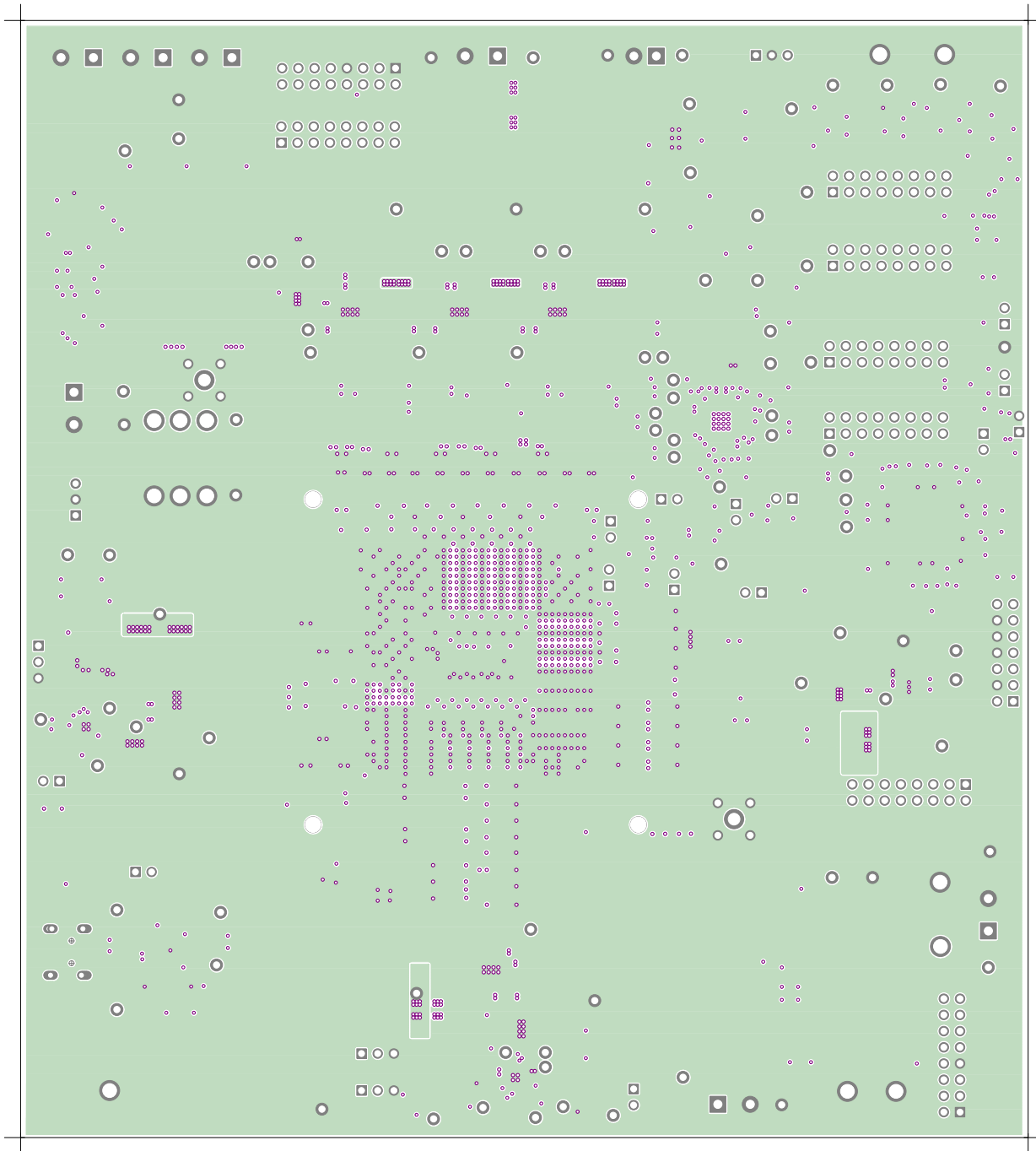
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
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Board No.	HPA751	Rev.	A			L8						
Date:	11/30/2010	Filename:	HPA751A.pcb	Engineer:	Nancy Zhang	PCB Dgnr:	Rama V	Modified Date:	Mon Nov 14, 2011		Time Stamp:	17:06:23



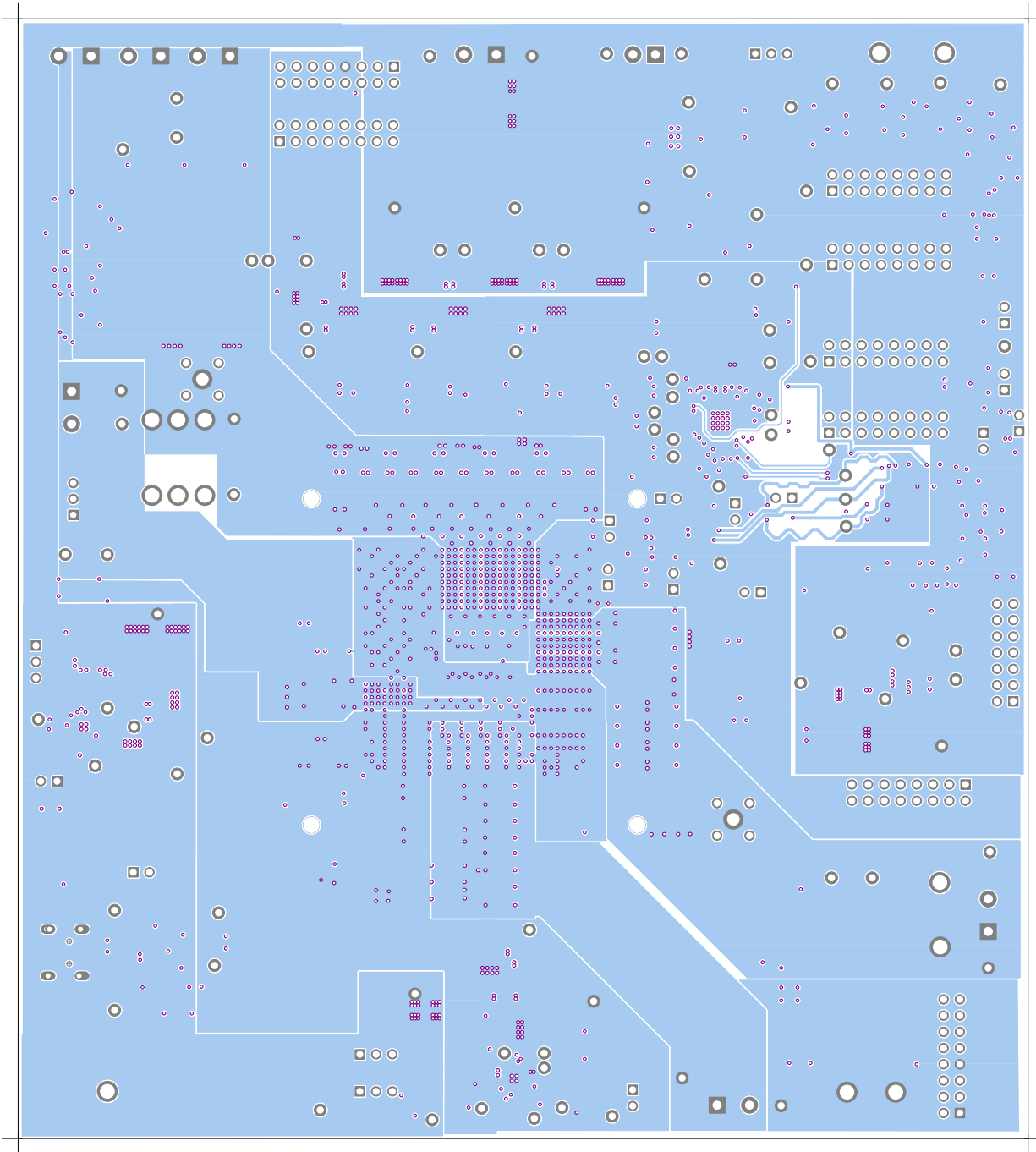
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Board No. HPA751	Rev. A	L2										
Date: 11/30/2010	Filename: HPA751A.pcb	Engineer: Nancy Zhang	PCB Design: Rama V	Modified Date: Mon Nov 14, 2011								Time Stamp: 17:06:24



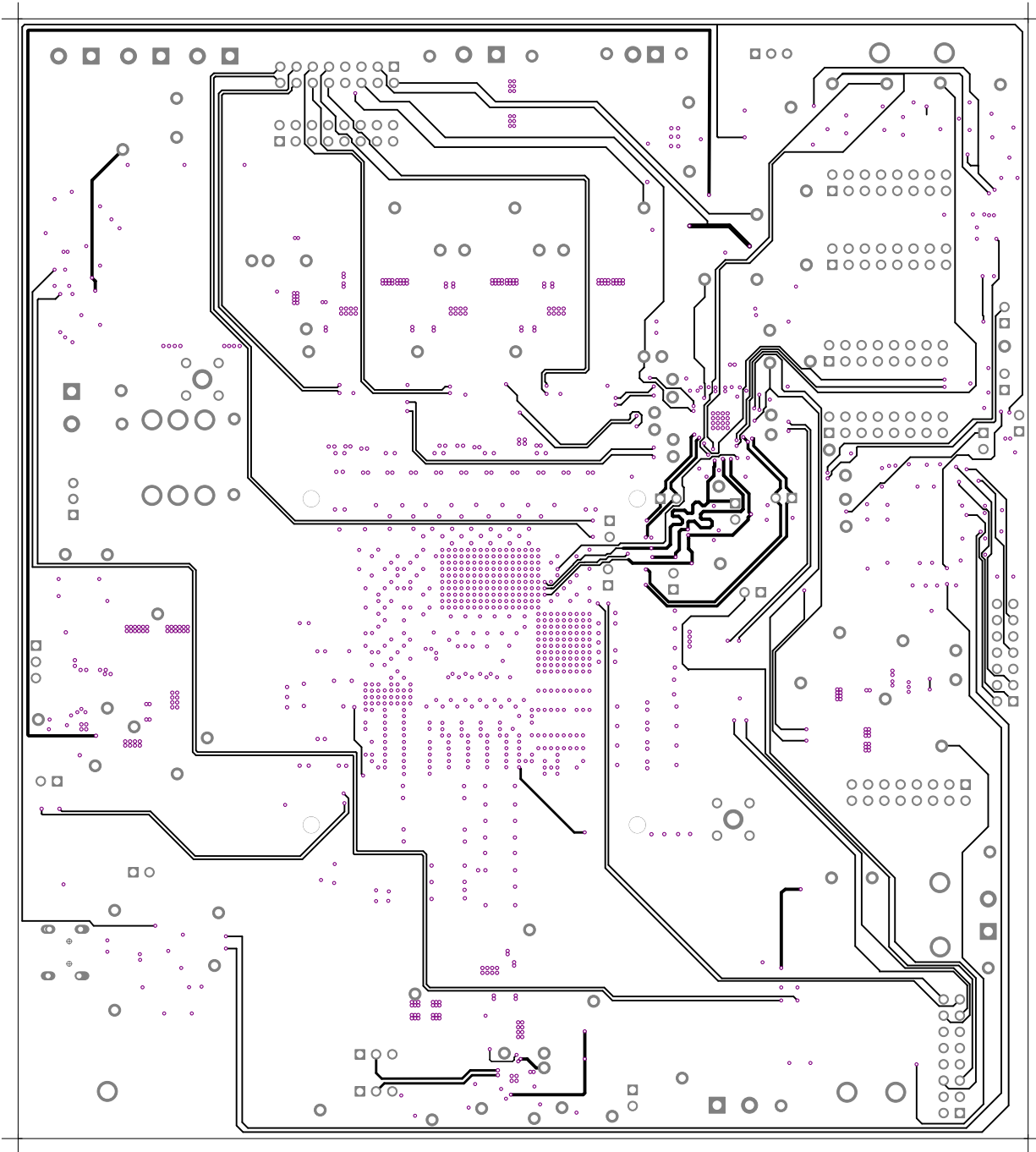
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Board No. HPA751	Rev. A		L3									
Date: 11/30/2010	Filename: HPA751A.pcb	Engineer: Nancy Zhang	PCB Dgnr: Rama V	Modified Date: Mon Nov 14, 2011								Time Stamp: 17:06:25



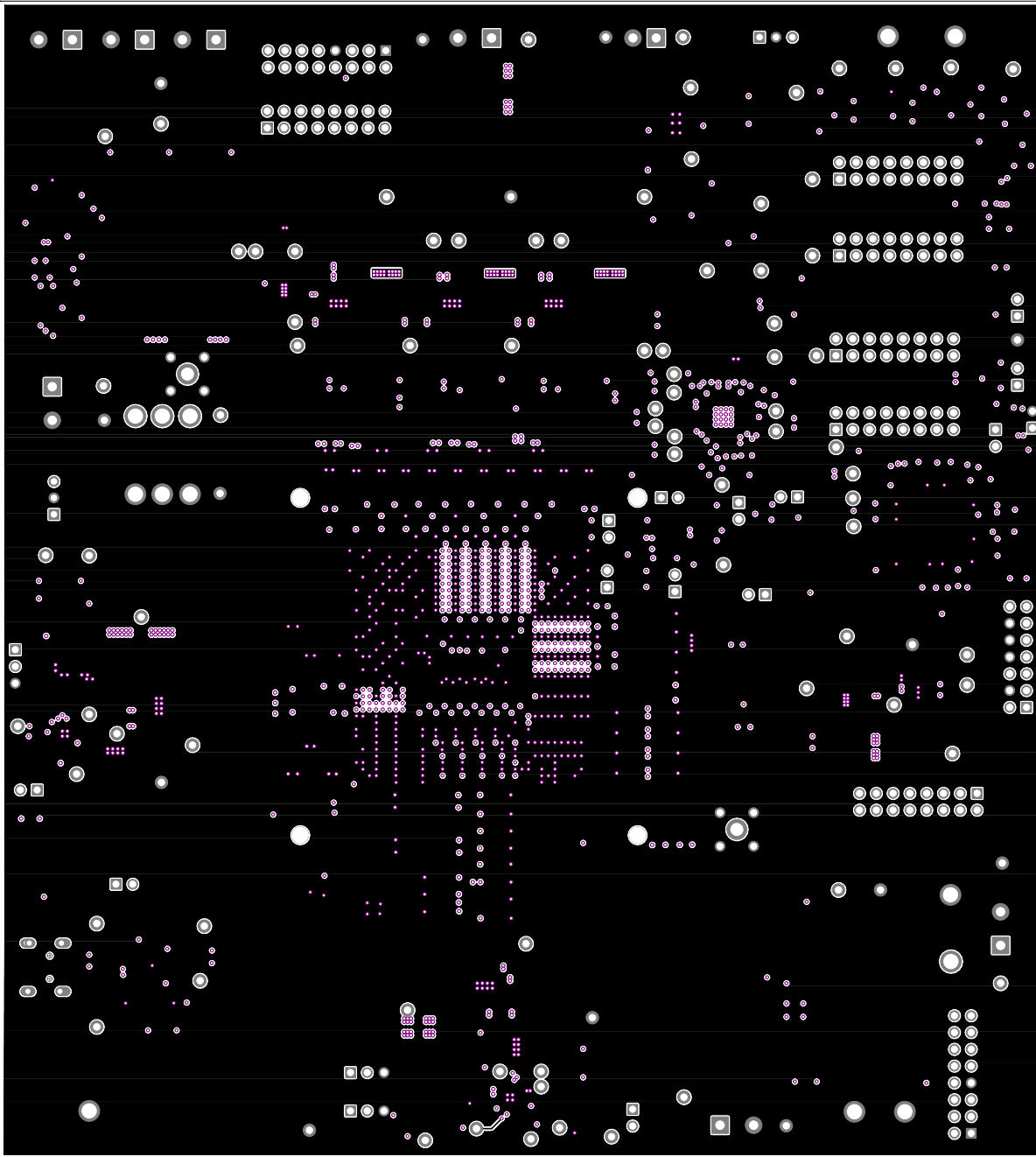
TEXAS INSTRUMENTS		Copper Layer Name						Silkscreen		Mask		Assembly		Fab Drawing
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Board No.	HPA751	Rev.	A				L4							
Date:	11/30/2010	Filename:	HPA751A.pcb	Engineer:	Nancy Zhang	PCB Dgnr:	Rama V	Modified Date:	Mon Nov 14, 2011			Time Stamp:	17:06:26	



TEXAS INSTRUMENTS		Copper Layer Name						Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal			Bot	Top	Bot	Top	Bot	Top	Bot		
Board No.	HPA751	Rev.	A			L5								
Date:	11/30/2010	Filename:	HPA751A.pcb	Engineer:	Nancy Zhang	PCB Dgnr:	Rama V	Modified Date:	Mon Nov 14, 2011			Time Stamp:	17:06:28	

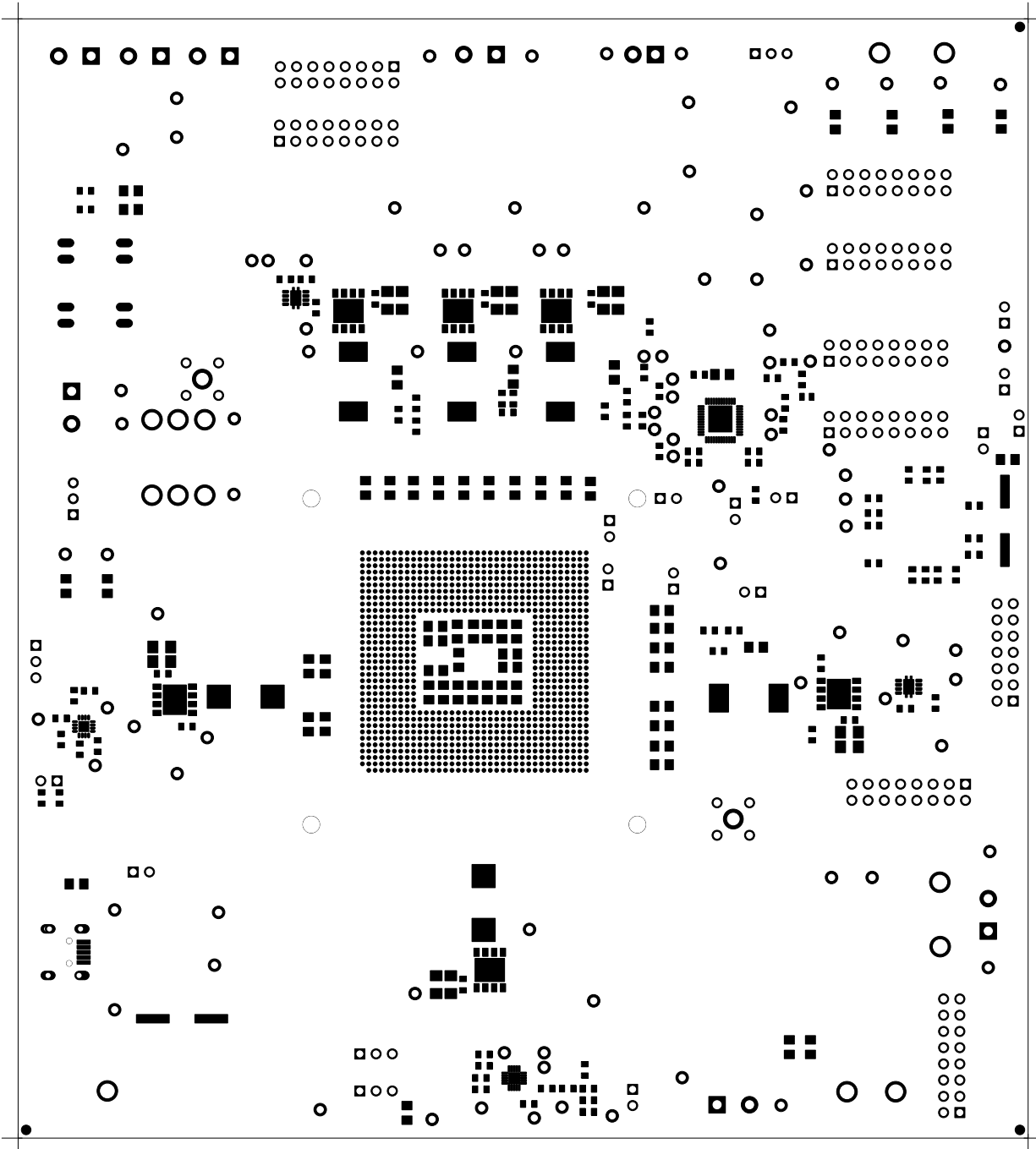


TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
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Board No.	HPA751	Rev.	A			L6						
Date:	11/30/2010	Filename:	HPA751A.pcb	Engineer:	Nancy Zhang	PCB Dgnr:	Rama V	Modified Date:	Mon Nov 14, 2011		Time Stamp:	17:06:28

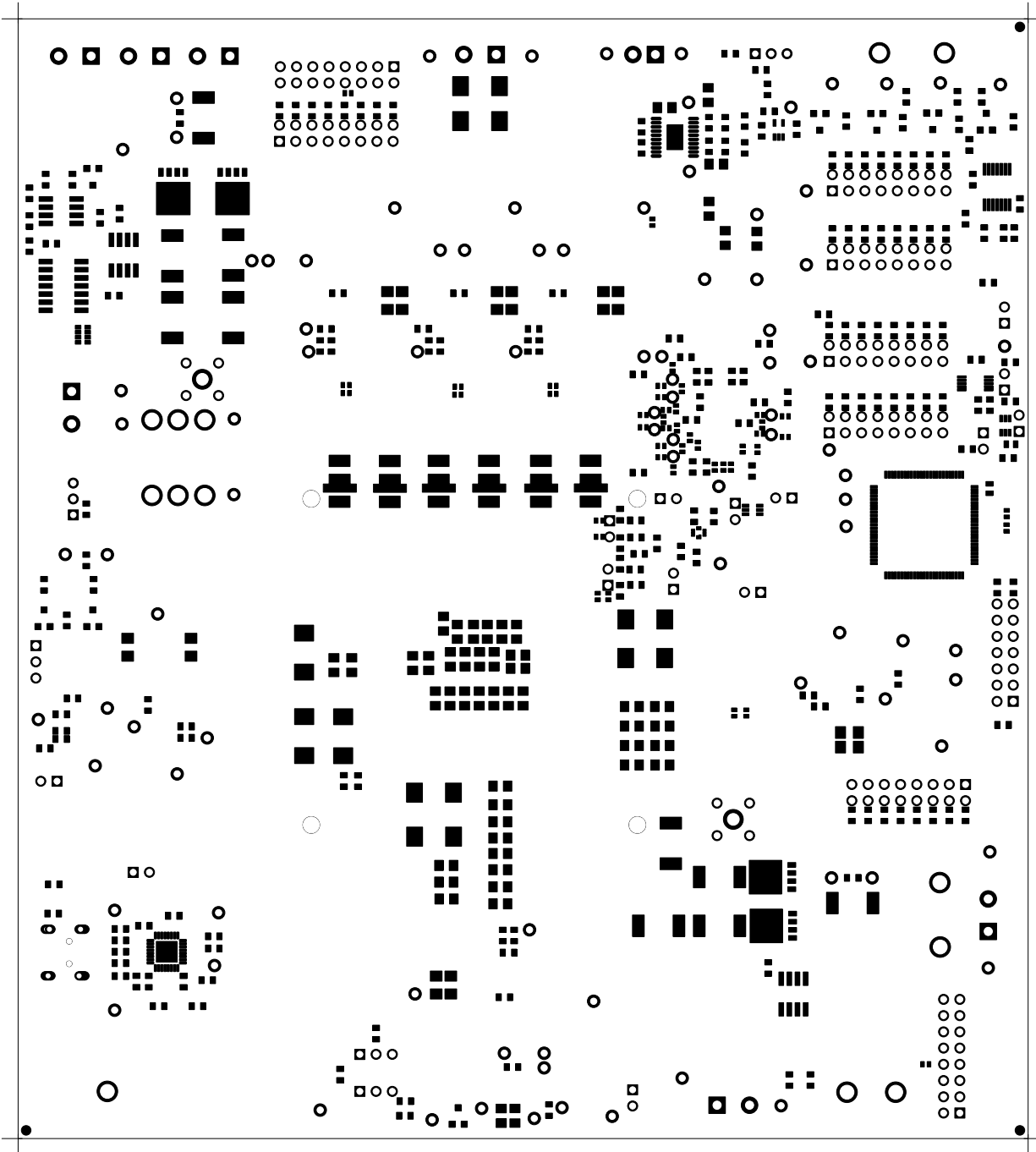


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Board No. HPA751	Rev. A				L7							
Date: 11/30/2010	Filename: HPA751A.pcb	Engineer: Nancy Zhang	PCB Dsgnr: Rama V	Modified Date: Mon Nov 14, 2011								Time Stamp: 17:06:29

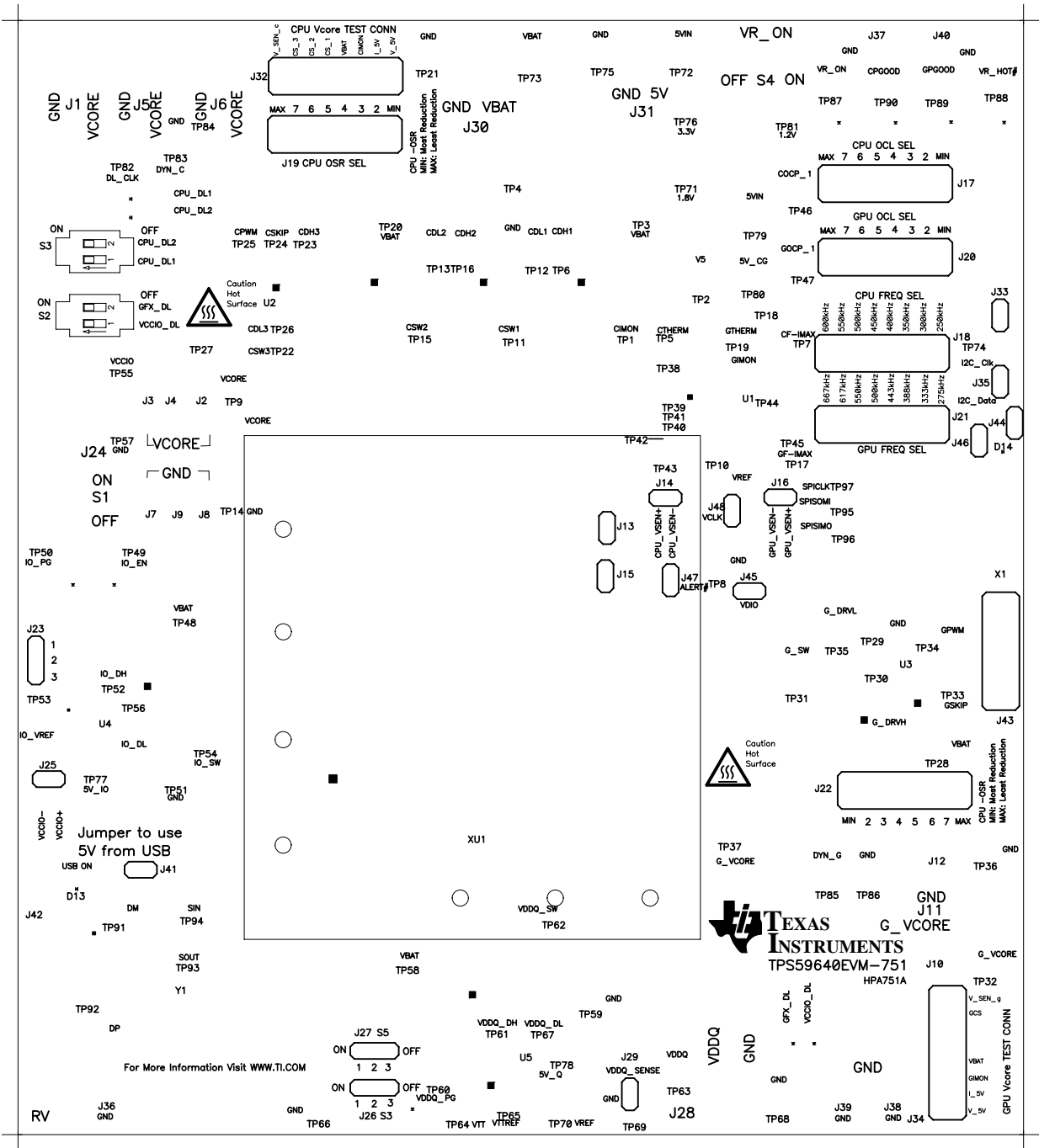




TEXAS INSTRUMENTS		Copper Layer Name						Silkscreen		Mask		Assembly		Fab Drawing
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Board No. HPA751	Rev. A									M1				
Date: 11/30/2010	Filename: HPA751A.pcb	Engineer: Nancy Zhang	PCB Dsgnr: Rama V	Modified Date: Mon Nov 14, 2011					Time Stamp: 17:06:29					



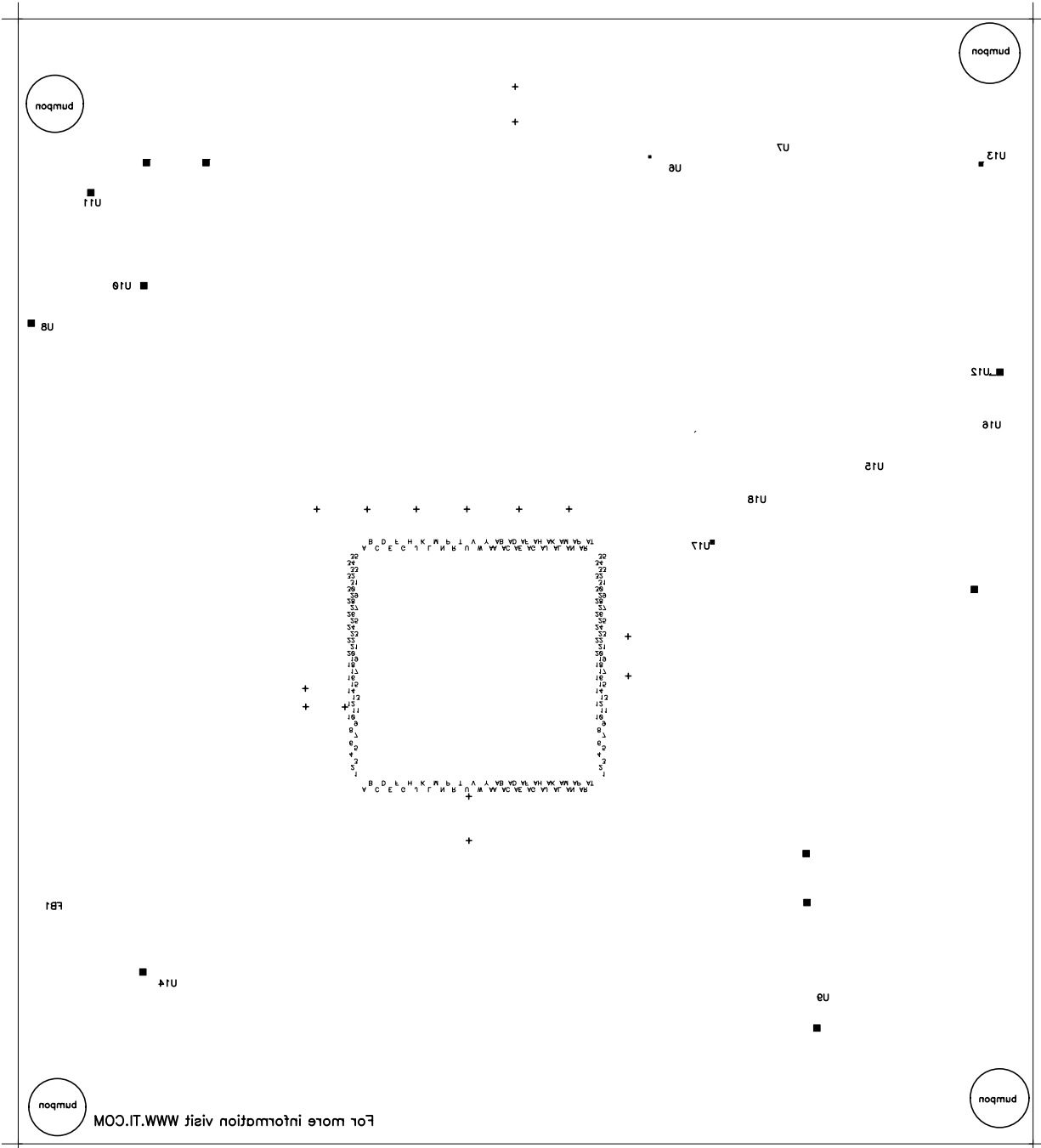
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Board No. HPA751	Rev. A										M8			
Date: 11/30/2010	Filename: HPA751A.pcb	Engineer: Nancy Zhang	PCB Dgnr: Rama V	Modified Date: Mon Nov 14, 2011					Time Stamp: 17:06:29					




**TEXAS INSTRUMENTS**  
 TPS59640EVM-751  
 HPA751A

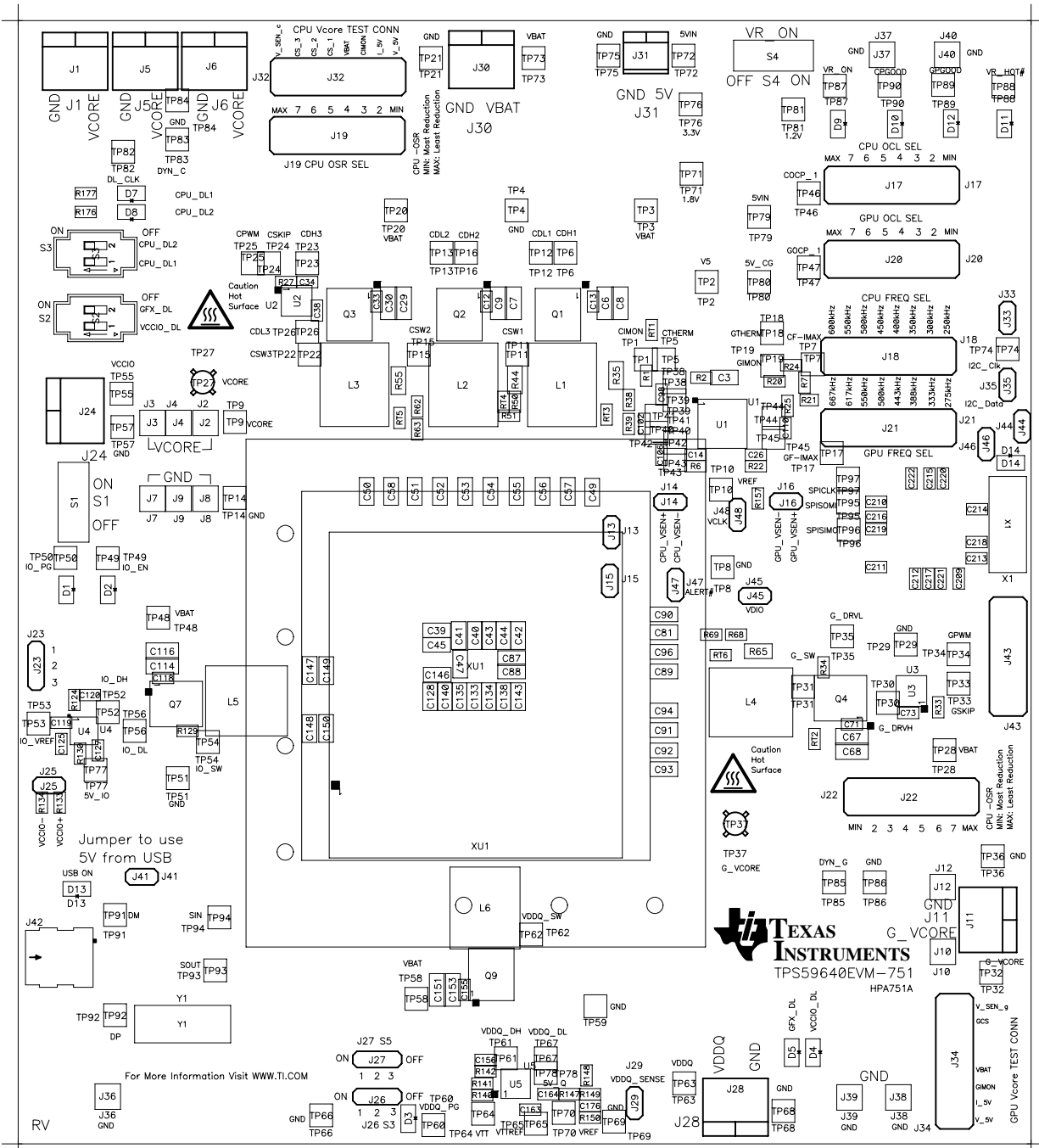
For More Information Visit [WWW.TI.COM](http://WWW.TI.COM)

TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		Mask		Assembly		Fab Drawing
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Board No.	HPA751	Rev.	A			S1					
Date:	11/30/2010	Filename:	HPA751A.pcb	Engineer:	Nancy Zhang	PCB Design:	Rama V	Modified Date:	Mon Nov 14, 2011	Time Stamp:	17:06:29



For more information visit [www.ti.com](http://www.ti.com)

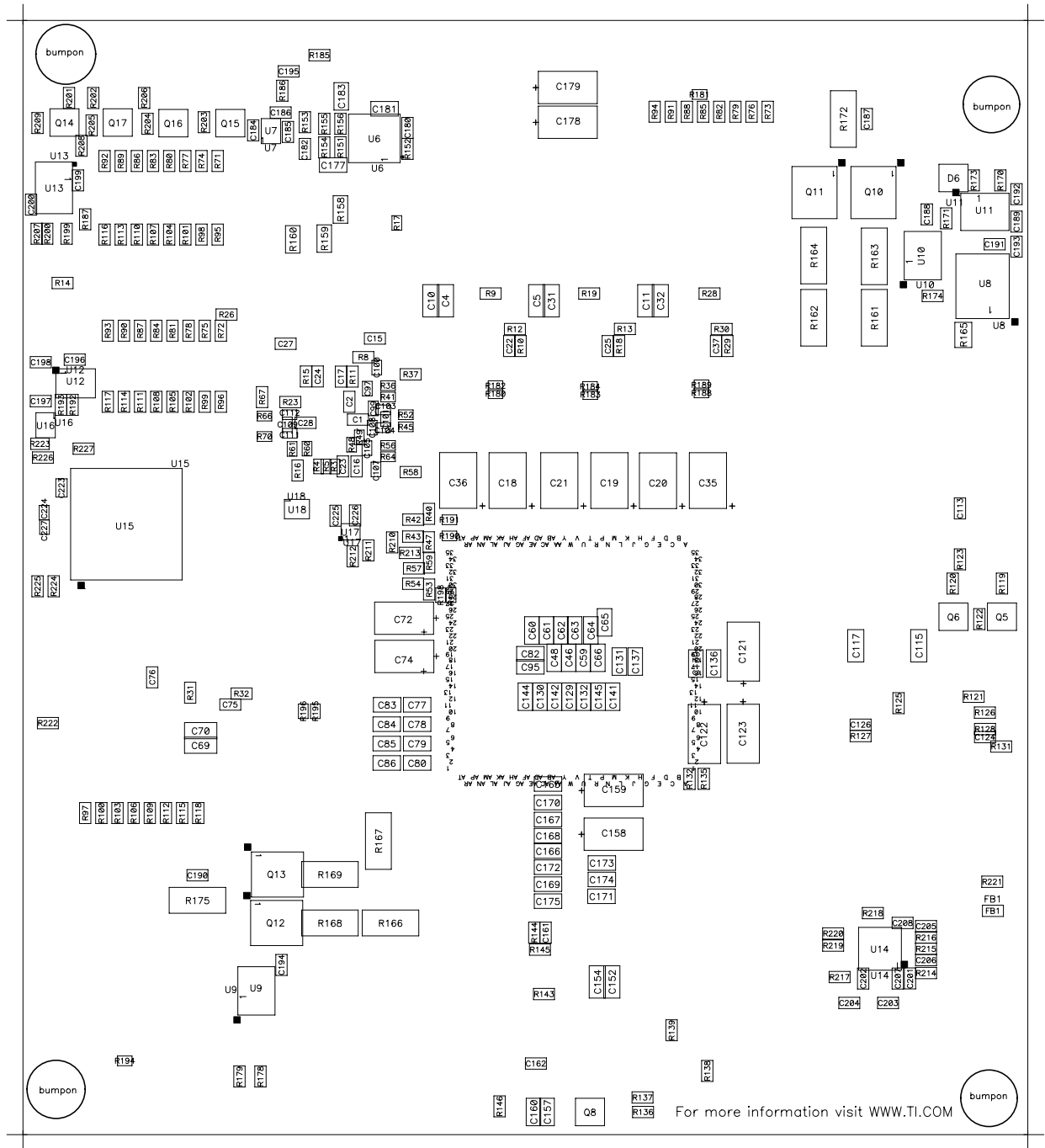
TEXAS INSTRUMENTS		Copper Layer Name						Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal				Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. HPA751	Rev. A								S8					
Date: 11/30/2010	Filename: HPA751A.pcb	Engineer: Nancy Zhang	PCB Dgnr: Rama V	Modified Date: Mon Nov 14, 2011				Time Stamp: 17:06:30						



**TEXAS INSTRUMENTS**  
 TPS59640EVM-751  
 HPA751A

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TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	HPA751	Rev.	A			S1				TA	
Date:	11/30/2010	Filename:	HPA751A.pcb	Engineer:	Nancy Zhang	PCB Dgnr:	Rama V	Modified Date:	Mon Nov 14, 2011	Time Stamp:	17:06:32



For more information visit [WWW.TI.COM](http://WWW.TI.COM)

Board No. HPA751		Rev. A		Copper Layer Name		Silkscreen		Mask		Assembly	
Date: 11/30/2011		Schematics: HPA751A.pcb		PCB Fabricator: Roma V		Modified Date: Mon Nov 14, 2011		Time Stamp: 17:08:35		Top Drawing	
HPA751		A		Internal		Top Bot		Top Bot		Top Bot	
8		28		BA		BA		BA		BA	

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